LISTING OF THE CLAIMS

CLAIM 1	CURRENTLY AMENDED
CLAIM 2	PREVIOUSLY AMENDED
CLAIM 3	ORIGINAL
CLAIM 4	ORIGINAL

TEXT OF CLAIMS CURRENTLY UNDER EXAMINATION

1. (currently amended) An adhesive comprising a sprayable adhesive composition having a viscosity within the range of 5.0 Pa.s or less, containing at least one dark and one light colored filler present in an amount from 5 to 50% by weight of the adhesive composition for each of the dark and light fillers, in which the adhesive comprises a solvent and an epoxy resin or a solvent and a combination of an electron donor resin and an electron acceptor resin.
2. (previously amended) The adhesive according to claim 1 in which the dark filler is carbon black.
3. (original) A method for laser marking the inactive surface of a semiconductor silicon die or wafer comprising
   (a) providing a sprayable adhesive composition having a viscosity within the range of 0.5 Pa.s to 5.0 Pa.s, containing at least one colored filler present in an amount up to 50% by weight of the adhesive composition,
   (b) spraying or jetting the adhesive composition onto the inactive surface of the semiconductor silicon die or wafer to a thickness within the range of 12.5 μm to 150 μm
   (c) curing the adhesive composition
   (d) marking the die or wafer by using a laser to burn or cut a mark or fiducial into the adhesive.
4. (original) The method according to claim 3 in which the sprayable adhesive is an epoxy resin or a combination of an electron donor resin and an electron acceptor resin.